



Click [here](#) for the 3D model.

Dimensions

Chip Size	0603
L	1.6mm +0.2/-0.15mm (0.063 in +0.008/-0.006 in)
W	0.81mm +0.2/-0.15mm (0.032 in +0.008/-0.006 in)
T	1.02mm MAX (0.04 in MAX)
B	0.41mm +/-0.2mm (0.016 in +/-0.008 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	368

General Information

Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 M-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	4.7 pF
Capacitance Tolerance	+/-0.25 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)